Application No.: 09/741,684
Appeal No.: 2006-0513
Amendment and RCE dated: April 12, 2006

AMENDMENTS TO THE CLAIMS

1. – 6. (Cancelled)

7. (Currently Amended) A suspension comprising:

a suspension bonding pad for electrically bonding a magnetic head terminal, wherein said bonding pad includes a metal pad having a bonding substance applied as a surface finishing material, the surface finishing material being heat treated prior to bonding to a surface; and

a slider bonding pad initially without bonding substance coupled to said suspension such that the bonding substance on said suspension bonding pad is reflowed so as to electrically couple the suspension bonding pad and the slider bonding pad wherein the suspension bonding pad comprises a disk drive.

8. (Previously Presented) The suspension as claimed in claim 7, wherein said bonding substance is solder.

9. (Previously Presented) The suspension as claimed in claim 7, wherein said bonding substance is a conductive polymer.

10. (Previously Presented) The suspension as claimed in claim 7, wherein said bonding substance is an adhesive.

11. (Previously Presented) The suspension as claimed in claim 7, wherein said bonding substance is a film.

12. (Previously Presented) The suspension as claimed in claim 8, wherein a bump height for the solder is approximately 50-300 μm, and a bump diameter for the solder is less than 180 μm.

13-18 (Cancelled)

19. (New) A suspension comprising:

a suspension bonding pad for electrically bonding a magnetic head terminal, wherein said bonding pad includes a metal pad having a bonding substance applied as a surface finishing material, the surface finishing material being heat treated prior to bonding to a surface; and

a slider bonding pad initially without bonding substance coupled to said suspension such that the bonding substance on said suspension bonding pad is reflowed so as to electrically couple the suspension bonding pad and the slider bonding pad, wherein the slider bonding pad enables the reuse of the suspension by removing the connection between a slider and the slider bonding pad with heat treatment.

20. (New) The suspension as claimed in claim 19, wherein said bonding substance is solder.

21. (New) The suspension as claimed in claim 19, wherein said bonding substance is a conductive polymer.

22. (New) The suspension as claimed in claim 19, wherein said bonding substance is an adhesive.

23. (New) The suspension as claimed in claim 19, wherein said bonding substance is a film.

24. (New) The suspension as claimed in claim 20, wherein a bump height for the solder is approximately 50-300 μm, and a bump diameter for the solder is less than 180 μm.

25. (New) A suspension comprising:

a suspension bonding pad for electrically bonding a magnetic head terminal, wherein said bonding pad includes a metal pad having a bonding substance applied as a surface finishing material, the surface finishing material being heat treated prior to bonding to a surface; and

a slider bonding pad initially without bonding substance coupled to said suspension such that the bonding substance on said suspension bonding pad is reflowed so as to electrically couple the suspension bonding pad and the slider bonding pad wherein the suspension further comprises several bonding bumps for bonding the suspension and a slider connection circuit.

26. (New) The suspension as claimed in claim 25, wherein said bonding substance is solder.

27. (New) The suspension as claimed in claim 25, wherein said bonding substance is a conductive polymer.

28. (New) The suspension as claimed in claim 25, wherein said bonding substance is an adhesive.

29. (New) The suspension as claimed in claim 25, wherein said bonding substance is a film.

30. (New) The suspension as claimed in claim 25, wherein the bonding bumps have a bump height for the solder is approximately 50-300 μm, and a bump diameter for the solder is less than 180 μm.